

Features

- AEC-Q101 Qualified
- Split Gate Trench MOSFET Technology
- Low $R_{DS(on)}$ & FOM
- Moisture Sensitivity Level 3
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

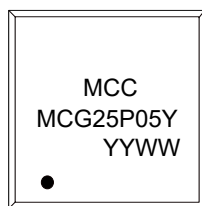
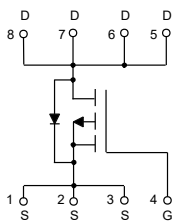
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 60°C/W Junction to Ambient (Steady-State) (Note2)
- Thermal Resistance: 1.7°C/W Junction to Case (Steady-State)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	-48	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I_D	$T_C=25^\circ C$	-25
		$T_C=100^\circ C$	-16
Pulsed Drain Current (Note3)	I_{DM}	-100	A
Total Power Dissipation (Note4)	P_D	74	W
Single Pulsed Avalanche Energy (Note5)	E_{AS}	81	mJ

Note:

1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ C$.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-case thermal resistance.
5. $V_{GS}=-10V, V_{DD}=-50V, R_G=25\Omega, L=0.5mH$.

Internal Structure and Marking Code

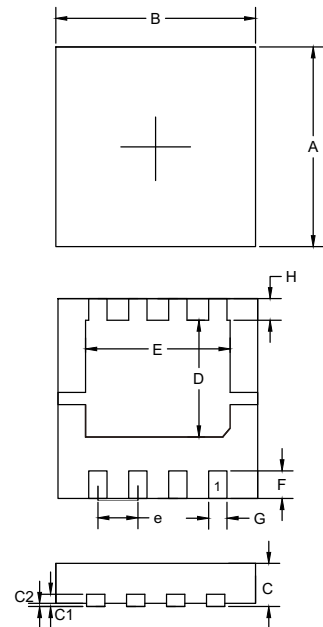


pin1

4 codes in total
YY is the year
WW is the week

**P-CHANNEL
MOSFET**

DFN3333



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.126	0.130	3.20	3.30	
B	0.126	0.130	3.20	3.30	
C	0.030	0.033	0.75	0.85	
C1	0.007	0.009	0.18	0.22	
C2	---	0.002	---	0.05	
D	0.071	0.079	1.80	2.00	
E	0.087	0.098	2.20	2.50	
F	0.016	0.020	0.40	0.50	
G	0.010	0.014	0.25	0.35	
H	0.012	0.016	0.30	0.40	
e	0.024	0.028	0.60	0.70	

Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-48			V
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-48V, V_{GS}=0V$			-1	μA
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.5	-2.1	-2.7	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-20A$		35	45	m Ω
		$V_{GS}=-4.5V, I_D=-10A$		47	61	
Gate Resistance	R_g	F=1 MHz, Open drain		12		Ω
Diode Characteristics						
Continuous Body Diode Current	I_S				-25	A
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=-20A$			-1.3	V
Reverse Recovery Time	t_{rr}	$I_F=-20A, dI_F/dt=100A/\mu s$		28.3		ns
Reverse Recovery Charge	Q_{rr}			20.2		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=-30V, V_{GS}=0V, f=1MHz$		1024		pF
Output Capacitance	C_{oss}			386		
Reverse Transfer Capacitance	C_{rss}			22		
Total Gate Charge	Q_g	$V_{DS}=-30V, V_{GS}=-10V, I_D=-20A$		17.4		nC
Gate-Source Charge	Q_{gs}			3.8		
Gate-Drain Charge	Q_{gd}			3.0		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=-30V, V_{GS}=-10V, R_{GEN}=6\Omega$		7.9		ns
Turn-On Rise Time	t_r			4.6		
Turn-Off Delay Time	$t_{d(off)}$			42.4		
Turn-Off Fall Time	t_f			15.7		

Curve Characteristics

Fig. 1 - Typical Output Characteristics

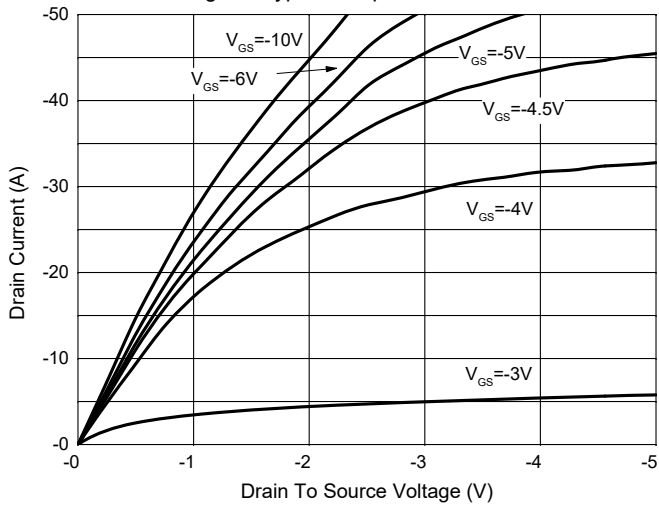


Fig. 2 - Transfer Characteristics

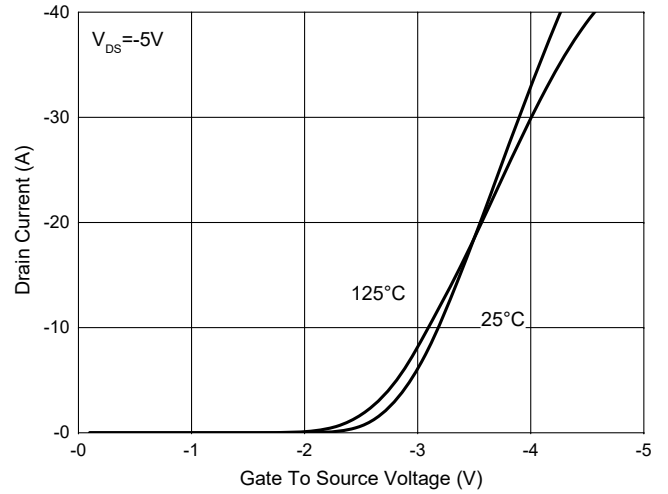


Fig. 3 - $R_{DS(ON)} - V_{GS}$

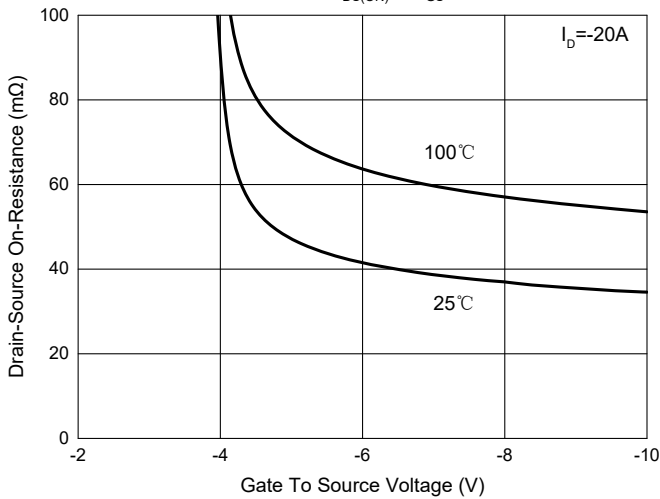


Fig. 4 - $R_{DS(ON)} - I_D$

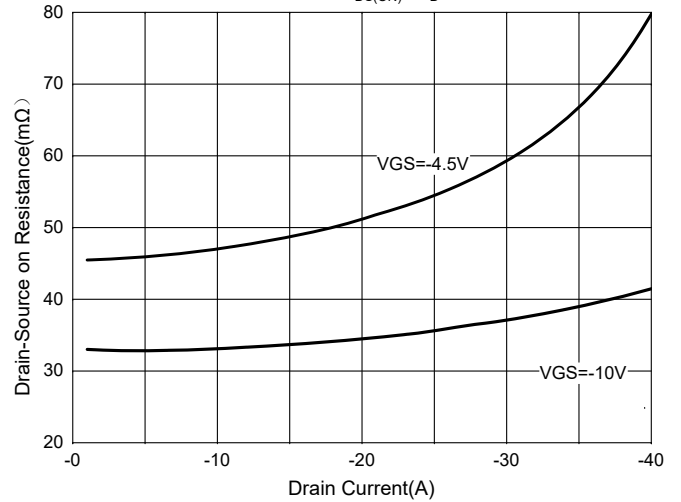


Fig. 5 - Capacitance Characteristics

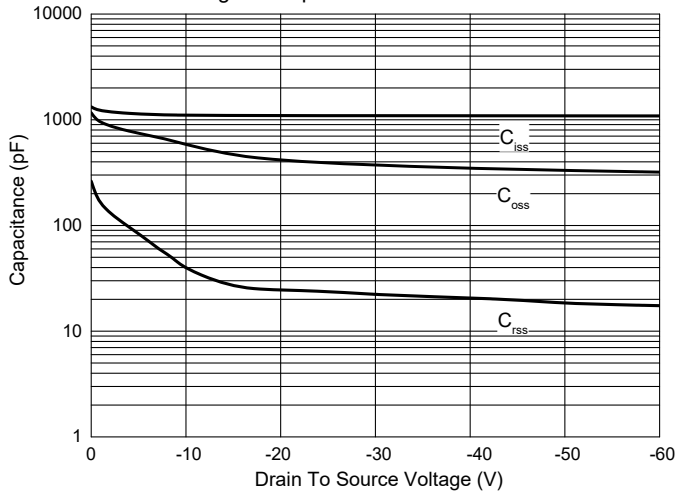
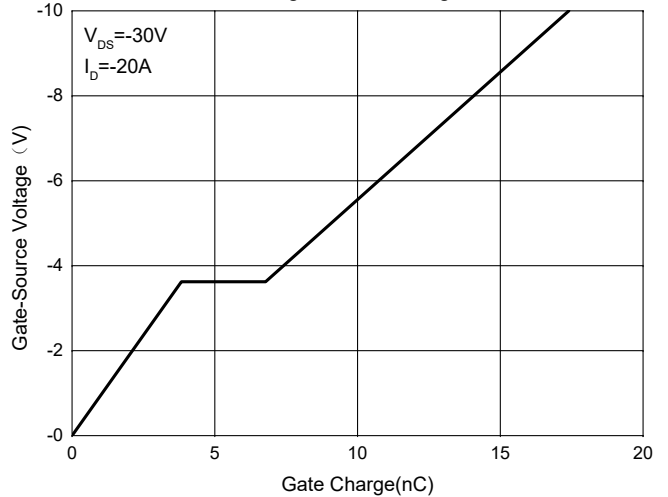


Fig. 6 - GateCharge



Curve Characteristics

Fig. 7 - Normalized Threshold Voltage

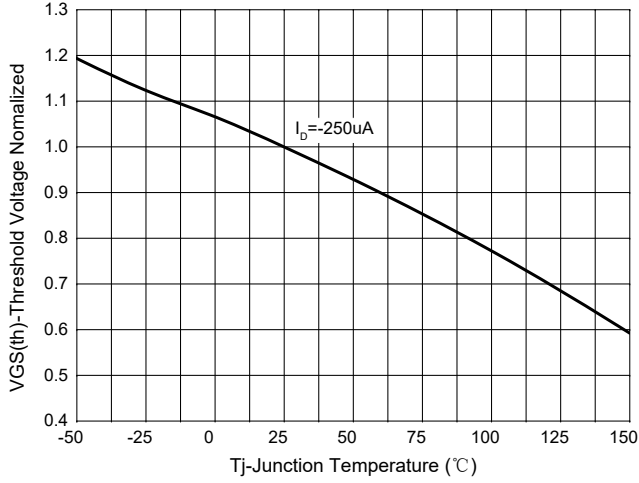


Fig.8-Normalized On Resistance Characteristics

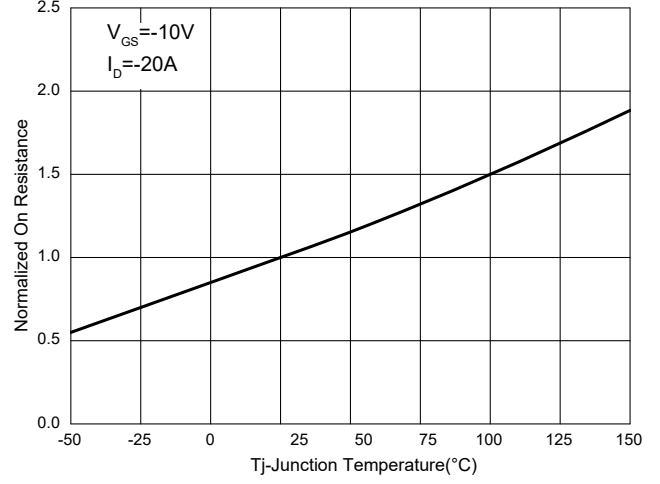


Fig. 9 - $I_s - V_{SD}$

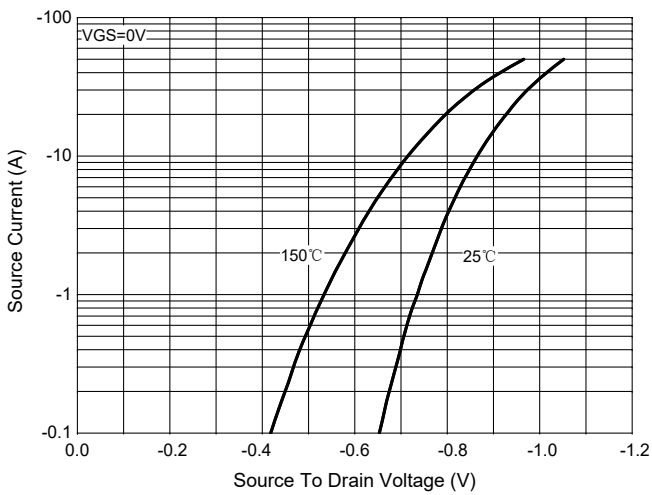


Fig. 10 - Drain Current

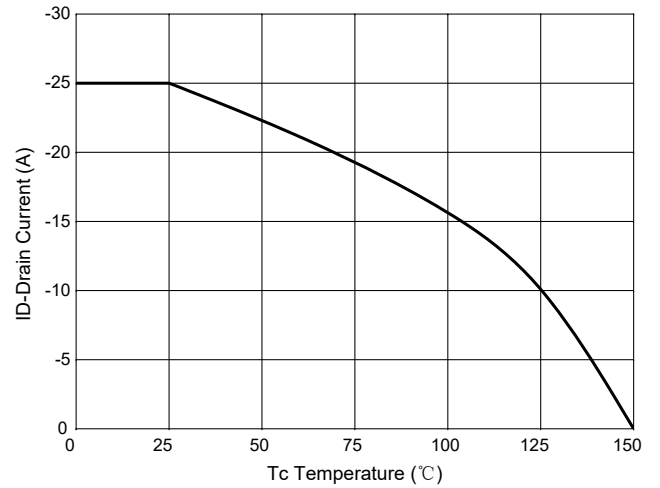
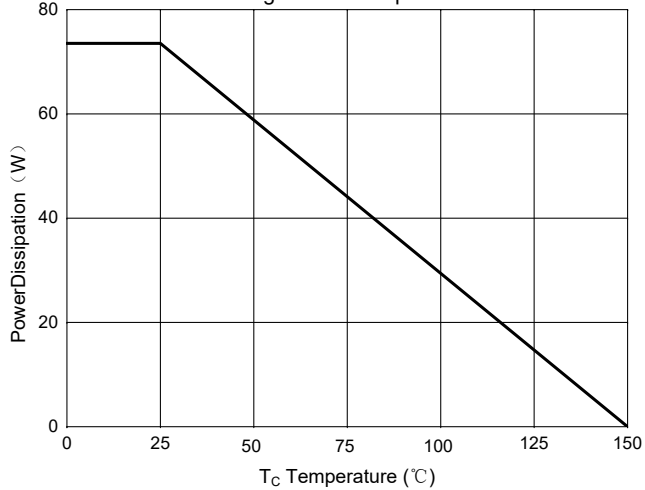
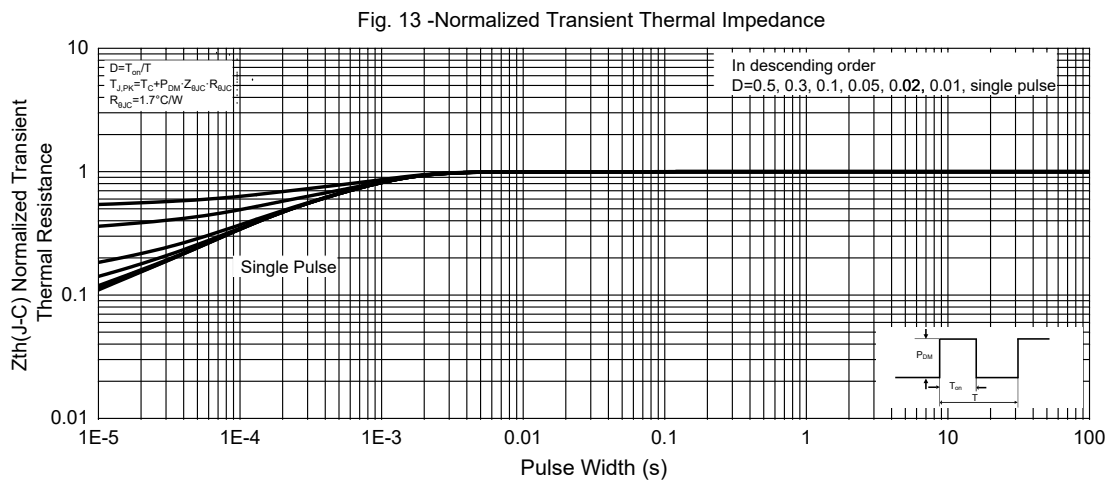
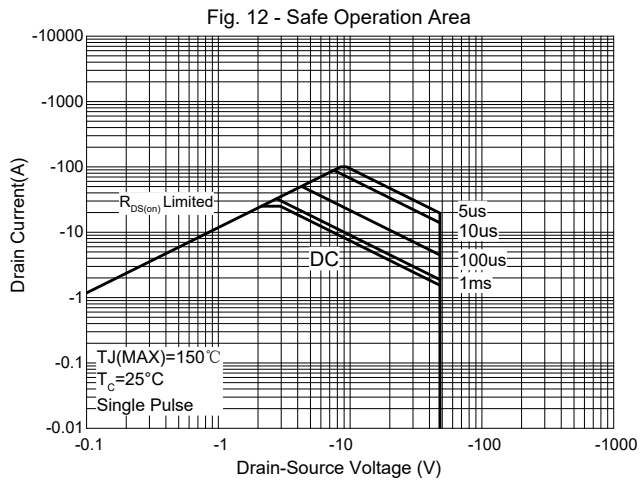


Fig.11-PD Dissipation



Curve Characteristics



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 5Kpcs/Reel

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